



Product Change Notification / NTDO-24ZJOF507

Date:

01-Aug-2023

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6422 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire as new wire material for selected PIC16F153xx, PIC16F183xx, PIC16F184xx, PIC16LF153xx, PIC16LF183xx, PIC16LF184xx, PIC18F04Q4xx, PIC18F05Q4xx and PIC18F06Q4xx device families available in 14L and 8L SOIC (3.90mm) package.

Affected CPNs:

[NTDO-24ZJOF507_Affected_CPN_08012023.pdf](#)

[NTDO-24ZJOF507_Affected_CPN_08012023.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire as new wire material for selected PIC16F153xx, PIC16F183xx, PIC16F184xx, PIC16LF153xx, PIC16LF183xx, PIC16LF184xx, PIC18F04Q4xx, PIC18F05Q4xx and PIC18F06Q4xx device families available in 14L and 8L SOIC (3.90mm) package.

Pre and Post Change Summary:

Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:August 1, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_NTDO-24ZJOF507_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

PIC16LF18323T-I/SLC01
PIC16F15313-I/SNC01
PIC16F15313T-I/SNC01
PIC16F15324-I/SLC02
PIC16F15324T-I/SLC02
PIC16F18324-E/SL024
PIC16F18324T-E/SL024
PIC18F06Q41-E/SL
PIC18F06Q40-E/SL
PIC18F06Q41-I/SL
PIC18F06Q40-I/SL
PIC18F06Q41T-I/SL
PIC18F06Q40T-I/SL
PIC18F04Q40-E/SL
PIC18F05Q40-E/SL
PIC18F04Q41-E/SL
PIC18F05Q41-E/SL
PIC18F04Q40-I/SL
PIC18F05Q40-I/SL
PIC18F04Q41-I/SL
PIC18F05Q41-I/SL
PIC18F04Q40T-I/SL
PIC18F05Q40T-I/SL
PIC18F04Q41T-I/SL
PIC18F05Q41T-I/SL
PIC16F18324-E/SL
PIC16LF18324-E/SL
PIC16F18324-I/SL
PIC16LF18324-I/SL
PIC16LF18324T-I/SL020
PIC16F18324T-I/SL027
PIC16F18324T-I/SL028
PIC16F18324T-I/SL
PIC16LF18324T-I/SL
PIC16F18324T-E/SL
PIC16F18325-E/SL
PIC16LF18325-E/SL
PIC16F18325-I/SL
PIC16LF18325-I/SL
PIC16F18325T-I/SL
PIC16LF18325T-I/SL
PIC16LF18313-E/SN
PIC16F18313-E/SN
PIC16LF18323-E/SL
PIC16F18323-E/SL
PIC16LF18313-I/SN

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PIC16F18313-I/SN

PIC16LF18323-I/SL

PIC16F18323-I/SL

PIC16LF18313T-I/SN

PIC16F18313T-I/SN

PIC16LF18323T-I/SL

PIC16F18323T-I/SL

PIC16F18313T-E/SN027

PIC16F18313T-E/SN030

PIC16F18313T-E/SN031

PIC16F18313T-E/SN

PIC16LF18323T-E/SL

PIC16F18323T-E/SL

PIC16F18424-E/SL

PIC16F18425-E/SL

PIC16LF18424-E/SL

PIC16LF18425-E/SL

PIC16F18424-I/SL

PIC16F18425-I/SL

PIC16LF18424-I/SL

PIC16LF18425-I/SL

PIC16F18424T-I/SL

PIC16F18425T-I/SL

PIC16LF18424T-I/SL

PIC16LF18425T-I/SL

PIC16F18424T-E/SL

PIC16F18426-E/SL

PIC16LF18426-E/SL

PIC16F18426-I/SL

PIC16LF18426-I/SL

PIC16F18426T-I/SL

PIC16LF18426T-I/SL

PIC16F18326-E/SL

PIC16LF18326-E/SL

PIC16F18326-I/SL

PIC16LF18326-I/SL

PIC16F18326T-I/SL

PIC16LF18326T-I/SL

PIC16F15325-E/SL

PIC16LF15325-E/SL

PIC16F15325-I/SL

PIC16LF15325-I/SL

PIC16F15325T-I/SL

PIC16LF15325T-I/SL

PIC16F15324-E/SL

PIC16LF15324-E/SL

PIC16F15324-I/SL

PIC16LF15324-I/SL

PIC16F15324T-I/SL

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PIC16LF15324T-I/SL

PIC16F15324T-E/SL

PIC16F15313-E/SN

PIC16LF15313-E/SN

PIC16F15323-E/SL

PIC16LF15323-E/SL

PIC16F15313-I/SN

PIC16LF15313-I/SN

PIC16F15323-I/SL

PIC16LF15323-I/SL

PIC16F15313T-I/SN021

PIC16LF15313T-I/SN023

PIC16F15313T-I/SN

PIC16LF15313T-I/SN

PIC16F15323T-I/SL

PIC16LF15323T-I/SL

PIC16F15313T-E/SN